

Amendments to the claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A method for manufacturing a metal master comprising the steps of:

forming a conductive film by an electroless plating method on a glass master having fine depressions and protrusions for forming an information recording region of an information recording disc;

forming an electrolytic plating layer by an electrolytic plating method on the conductive film; and

removing the conductive film and the electrolytic plating layer from the glass master to provide a metal master, ~~wherein~~wherein:

wherein the conductive film is formed to have a thickness of 35 to 200 nm.

2. (Currently Amended) The method for manufacturing a metal master according to claim 1, wherein

_____ the conductive film is formed to have a thickness of 40 nm or more.

3. (Currently Amended) The method for manufacturing a metal master according to claim 1, wherein

_____ the conductive film is formed to have a thickness of 45 nm or more.

4. (Currently Amended) The method for manufacturing a metal master according to claim 1, wherein

_____ the conductive film is formed to have a thickness of 50 nm or more.

5. (Currently Amended) The method for manufacturing a metal master according to claim 1, wherein

_____ the conductive film is formed to have a thickness of 150 nm or less.

6. (Currently Amended) The method for manufacturing a metal master according to claim 1, wherein

_____ the conductive film is formed to have a thickness of 120 nm or less.

7. (Currently Amended) The method for manufacturing a metal master according to claim 1, wherein

_____ the conductive film is formed to have a thickness of 90 nm or less.

8. (Currently Amended) The method for manufacturing a metal master according to claim 1, wherein

_____the conductive film is formed to have a thickness of 60 nm or less.

9. (Currently Amended) The method for manufacturing a metal master according to claim 1, wherein

_____the conductive film is formed to have a thickness of 55 nm or less.

10. (Currently Amended) A method for manufacturing a metal master comprising the steps of:

forming a conductive film by an electroless plating method on a glass master having fine depressions and protrusions for forming an information recording region of an information recording disc;

forming an electrolytic plating layer by an electrolytic plating method on the conductive film; and

removing the conductive film and the electrolytic plating layer from the glass master to provide a metal master, ~~wherein~~ master;

wherein the conductive film is formed to have a thickness greater than a step height of the fine depressions and protrusions of the glass master.

11. (Currently Amended) A metal master comprising a conductive film having copied fine depressions and protrusions for forming an information recording region of an information recording disc, and an electrolytic plating layer formed on the conductive film, wherein

_____the conductive film has a thickness in the range of 35 to 200 nm and is greater than a step height of the fine depressions and protrusions.

12. (Currently Amended) The metal master according to claim 11, wherein
_____the thickness of the conductive film is 40 nm or more.

13. (Currently Amended) The metal master according to claim 11, wherein
_____the thickness of the conductive film is 45 nm or more.

14. (Currently Amended) The metal master according to claim 11, wherein
_____the thickness of the conductive film is 50 nm or more.

15. (Currently Amended) The metal master according to claim 11, wherein
_____the thickness of the conductive film is 150 nm or less.

16. (Currently Amended) The metal master according to claim 11, wherein
_____the thickness of the conductive film is 120 nm or less.

17. (Currently Amended) The metal master according to claim 11, wherein
_____the thickness of the conductive film is 90 nm or less.

18. The metal master according to claim 11, wherein

_____the thickness of the conductive film is 60 nm or less.

19. (Currently Amended) The metal master according to claim 11, wherein

_____the thickness of the conductive film is 55 nm or less.